



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



# UNR31A0G

## Silicon PNP epitaxial planar type

For digital circuits

### ■ Features

- Suitable for high-density mounting and downsizing of the equipment
- Contribute to low power consumption

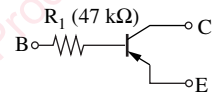
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{\text{CBO}}$	-50	V
Collector-emitter voltage (Base open)	$V_{\text{CEO}}$	-50	V
Collector current	$I_{\text{C}}$	-80	mA
Total power dissipation	$P_{\text{T}}$	100	mW
Junction temperature	$T_{\text{j}}$	125	$^\circ\text{C}$
Storage temperature	$T_{\text{stg}}$	-55 to +125	$^\circ\text{C}$

### ■ Package

- Code  
SSSMINI3-F2
- Marking Symbol: CD
- Pin Name
  - 1: Base
  - 2: Emitter
  - 3: Collector

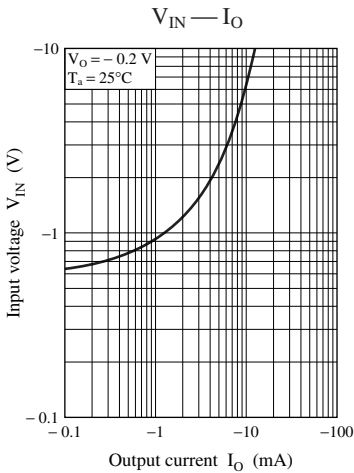
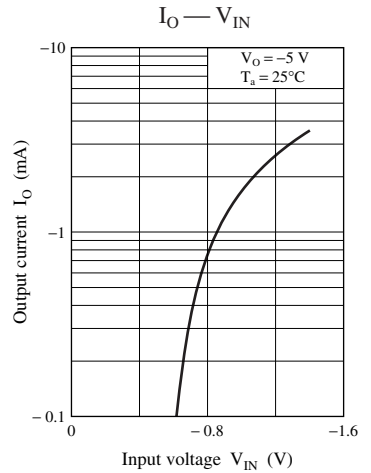
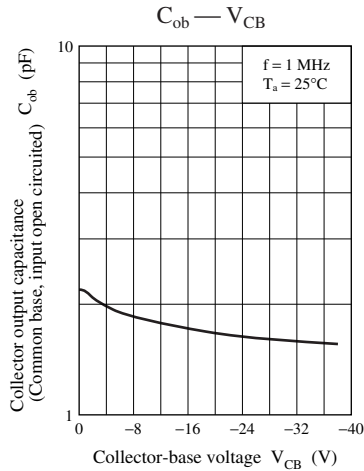
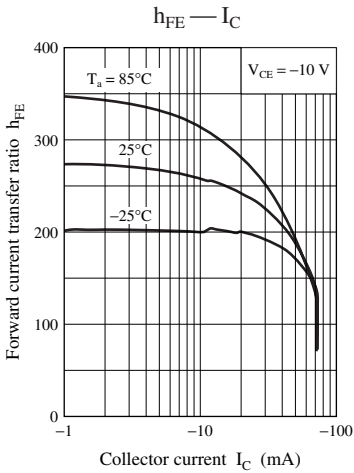
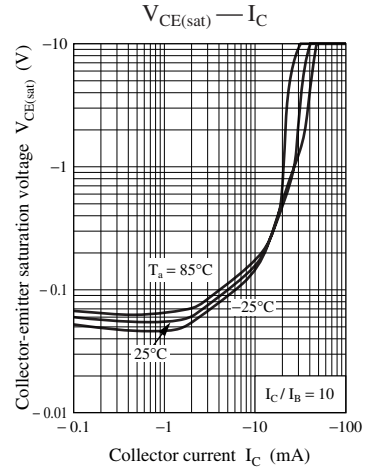
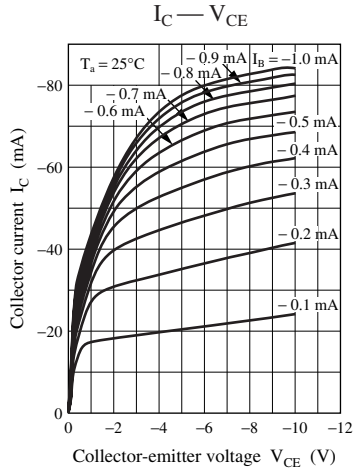
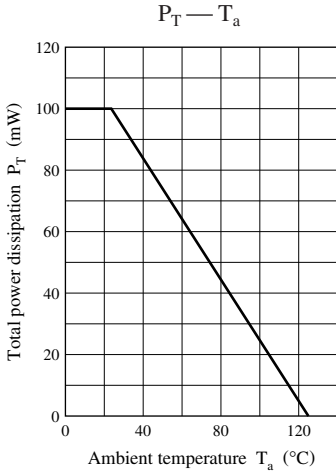
### ■ Internal Connection



### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

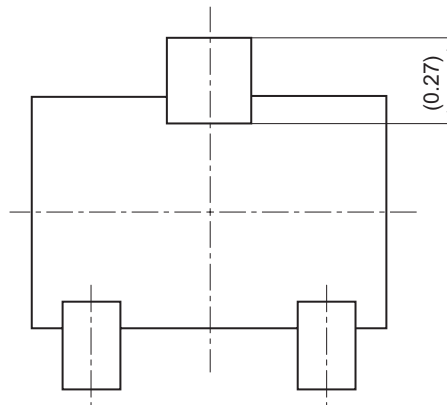
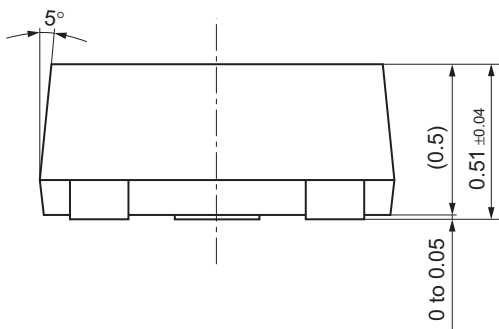
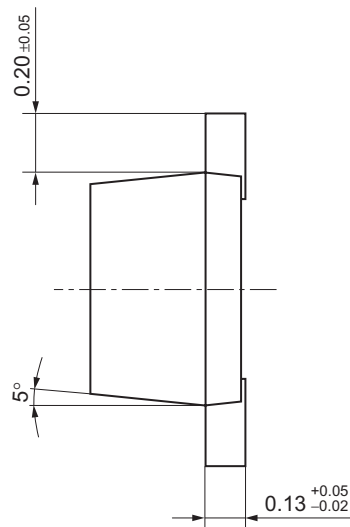
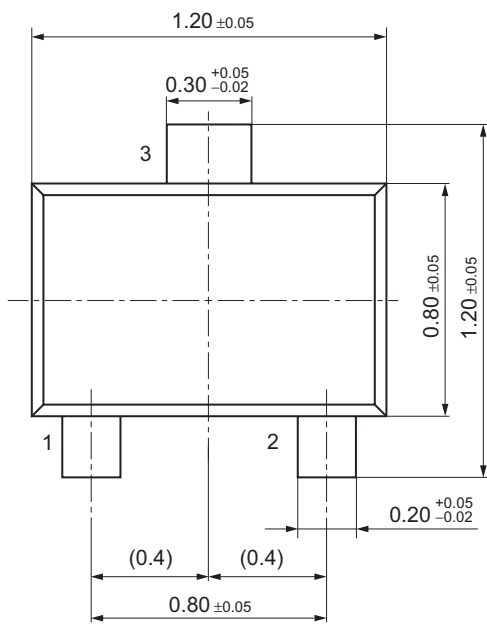
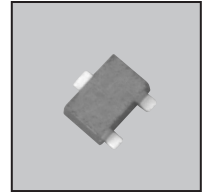
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	$V_{\text{CBO}}$	$I_{\text{C}} = -10 \mu\text{A}$ , $I_{\text{E}} = 0$	-50			V
Collector-emitter voltage (Base open)	$V_{\text{CEO}}$	$I_{\text{C}} = -2 \text{ mA}$ , $I_{\text{B}} = 0$	-50			V
Collector-base cutoff current (Emitter open)	$I_{\text{CBO}}$	$V_{\text{CB}} = -50 \text{ V}$ , $I_{\text{E}} = 0$			-0.1	$\mu\text{A}$
Collector-emitter cutoff current (Base open)	$I_{\text{CEO}}$	$V_{\text{CE}} = -50 \text{ V}$ , $I_{\text{B}} = 0$			-0.5	$\mu\text{A}$
Emitter-base cutoff current (Collector open)	$I_{\text{EBO}}$	$V_{\text{EB}} = -6 \text{ V}$ , $I_{\text{C}} = 0$			-0.01	mA
Forward current transfer ratio	$h_{\text{FE}}$	$V_{\text{CE}} = -10 \text{ V}$ , $I_{\text{C}} = -5 \text{ mA}$	160		460	—
Collector-emitter saturation voltage	$V_{\text{CE(sat)}}$	$I_{\text{C}} = -10 \text{ mA}$ , $I_{\text{B}} = -0.3 \text{ mA}$			-0.25	V
Output voltage high-level	$V_{\text{OH}}$	$V_{\text{CC}} = -5 \text{ V}$ , $V_{\text{B}} = -0.5 \text{ V}$ , $R_{\text{L}} = 1 \text{ k}\Omega$	-4.9			V
Output voltage low-level	$V_{\text{OL}}$	$V_{\text{CC}} = -5 \text{ V}$ , $V_{\text{B}} = -2.5 \text{ V}$ , $R_{\text{L}} = 1 \text{ k}\Omega$			-0.2	V
Input resistance	$R_{\text{I}}$		-30%	47	+30%	$\text{k}\Omega$
Transition frequency	$f_{\text{T}}$	$V_{\text{CB}} = -10 \text{ V}$ , $I_{\text{E}} = 1 \text{ mA}$ , $f = 200 \text{ MHz}$		80		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



SSSMini3-F2

Unit: mm



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